

**MIRKA**

**IMPROVED  
THERMAL  
CONTROL**



# Mirka<sup>®</sup> Cafro HP

Higher removal in less time



# HP Hybrid Bond family

Mirka® Cafro's new HP hybrid bond sets the new industry standard for high material removal.

## ▶ Faster grinding requires higher performance

Higher spindle speed, increased coolant pressures and superfiltration are the industry trends in tool grinding. Our high performance HP wheel enables substantial improvements in material removal ratio, productivity, finishing quality, tool life and costs.

## ▶ Improved thermal control

The new Mirka® Cafro HP Bond with higher porosity and better grinding residue removal enables higher material removal rates with improved thermal control. For optimal HP bond performance, a sufficiently high coolant pressure and proper filtration are essential.

## ▶ Engineered for efficient removal

The HP hybrid bond family is engineered for fluting operations with need for efficient removal. In optimal working conditions, material removal rates on carbide can be improved up to 25%. CBN wheels with HP hybrid bond can remove twice as much material compared to resin bond CBN wheels.

## ▶ A single pass can be enough

The HP hybrid bond provides good surface finishing with a single pass, with no need for multiple steps. The optimal grit sizes are D64 for diamond wheels and B91 for CBN wheels.